HIGH DENSITY DOUBLE SIDED SINGLE INLINE MEMORY MODULE

ABSTRACT OF THE DISCLOSURE

A high density double sided single inline memory module (140) comprising a printed circuit board (132) and first and second integrated circuit modules (130) respectively attached to the first and second sides (134, 136) of the printed circuit board (132), wherein the first and second integrated circuit modules (130) each including first and second integrated circuit packages (30) stackably and electrically connected together is disclosed.

Figure 1